

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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AF, 2200

Applicant: Frank O'Mahony et al.

Title: LOW LOSS INTERCONNECT STRUCTURE FOR USE IN MICROELECTRONIC CIRCUITS

Docket No.: 884.405US1  
Filed: June 27, 2001  
Examiner: Ahmed Sefer  
Customer No.: 21186



Serial No.: 09/893023  
Due Date: October 16, 2003  
Group Art Unit: 2826  
Confirmation No.: 3406

**MS AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response Under 37 CFR 1.116 (10 Pages).
- ☒ Communication Concerning Related Patents (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Customer Number 21186

By: David R. Cochran  
Atty: David R. Cochran  
Reg. No. 46,632

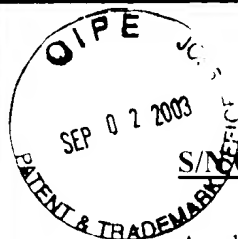
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21 day of August, 2003.

KACIA LEE  
Name

Kacia Lee  
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
(GENERAL)

**Customer Number 21186**



S/N 09/893023

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Frank O'Mahony et al.

Examiner: Ahmed Sefer

Serial No.: 09/893023

Group Art Unit: 2826

Filed: June 27, 2001

Docket: 884.405US1

Title: LOW LOSS INTERCONNECT STRUCTURE FOR USE IN  
MICROELECTRONIC CIRCUITS

Assignee: Intel Corporation

Customer No.: 21186

COMMUNICATION CONCERNING RELATED PATENTSMail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related patents in the above-identified patent application:

| <u>Patent No.</u> | <u>Serial No.</u> | <u>Filing Date</u> | <u>Attorney Docket</u> |
|-------------------|-------------------|--------------------|------------------------|
| 6,522,186         | 09/893,067        | June 27, 2001      | 884.431US1             |

Respectfully submitted,

FRANK O'MAHONY ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
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By

David R. Cochran  
David R. Cochran  
Reg. No. 46,632

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Name

KACIA LEE

Signature

Kacia Lee

**EXPEDITED PROCEDURE – EXAMINING GROUP 2826**

**S/N 09/893023**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Frank O'Mahony et al.

Examiner: Ahmed Sefer

Serial No.: 09/893023

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Filed: June 27, 2001

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Assignee: Intel Corporation

Customer No.: 21186

**AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116**

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In response to the final Office Action mailed July 16, 2003, please amend the application as follows: